

L Number	Hits	Search Text	DB	Time stamp
-	8421	encapsul\$ and metal and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:05
-	5948	encapsul\$ and metal and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:03
-	290	encapsul\$ and (metal adj sheets) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 14:55
-	402	encapsul\$ and (metal adj plates) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 15:27
-	96	(encapsul\$ with (metal adj layers)) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 15:44
-	12	(encapsul\$ with (metal adj films)) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 15:36
-	2	(encapsul\$ with (metal adj regions)) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 15:37
-	6	(encapsul\$ with (metal adj portions)) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 15:40
-	18	(encapsul\$ with (metal adj lines)) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 15:41
-	2	6489572.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:03
-	887	encapsul\$ and metal and (pcb or (printed adj circuit adj board)) and (injection adj molding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:07
-	726	encapsul\$ and metal and (pcb or (printed adj circuit adj board)) and (injection adj molding) and plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:09
-	1	encapsul\$ and metal and (pcb or (printed adj circuit adj board)) and (injection adj molding) and plastic and (middle adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:08
-	3	(encapsul\$ with (stacked adj metal)) and (pcb or (printed adj circuit adj board)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:56

-	2	(counterdoped adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:21
-	1	(counter adj doped adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:22
-	0	(double adj doped adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:23
-	0	(double adj diffused adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:23
-	0	(double adj implanted adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:23
-	0	(double adj dopant adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:23
-	0	(double adj diffusion adj collector) with (buried adj collector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:25
-	219	double adj collectors	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:42
-	1	6475831.pn. and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:43
-	776	encapsulated adj metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 16:57
-	41	(encapsulated adj metal) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:01
-	4	(encapsulated adj foil) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:02
-	7	(encapsulated adj metallic) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:06
-	253	257/708.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:28

-	144	257/709.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:32
-	429	257/710.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:42
-	154	257/711.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 17:51
-	182	257/699.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 18:29
-	1275	(lga or (land adj grid adj array)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 18:48
-	252	(substrate with (metal adj sheets)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 18:56
-	18	(substrate with (metal adj lands)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:19
-	42	(substrate with (metal adj regions)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 19:00
-	92	(substrate with (metal adj portions)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 19:06
-	160	(substrate with (metal adj strips)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 19:12
-	369	(substrate with (metal adj (films or layers))) with (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:04
-	18	(substrate with (metal adj lines)) with (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:07
-	113	(substrate with (metal adj plates)) with (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:08
-	0	(substrate with (contductive adj lands)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:29

-	128	(substrate with (conductive adj lands)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:24
-	484	(substrate with (conductive adj lines)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:25
-	33	substrate near (pcb or (printed adj circuit adj board)) near array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:27
-	0	(substrate with (metal adj array)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:30
-	0	(substrate same (metal adj array)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:30
-	3	(substrate and (metal adj array)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:31
-	204	(substrate and (metal near array)) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:43
-	12	(metal adj array) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:46
-	5	(metal adj sheet adj array) and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:47
-	19	metal adj sheet adj array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:48
-	125	metal adj (plate or line or strip or land) adj array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 20:49

L Number	Hits	Search Text	DB	Time stamp
1	2	6489572.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:58
2	1	6489572.pn. and plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:45
3	0	6489572.pn. and industrial	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:45
4	0	6489572.pn. and injection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:45
5	108	stacked adj metal adj sheets	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:58
6	351	257/798.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 16:25
7	0	(substrate adj structure) and (middle adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 16:42
8	34	(substrate adj structure) and (side adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 16:46
9	1	(substrate adj structure) and (center adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 16:47
10	5	(tab or (tape adj automated adj bonding)) and stacked and encapsula\$ and ((middle or center) adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 16:50
12	228	((middle or center) adj board) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 16:50
-	7	(tab or (tape adj automated adj bonding)) and stacked and multilayer and encapsula\$ and leadless and (flip adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:03
-	10	(tab or (tape adj automated adj bonding)) and stacked and multilayer and encapsula\$ and leadless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:04
-	47	(tab or (tape adj automated adj bonding)) and stacked and encapsula\$ and leadless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 15:04

-	1696	(tab or (tape adj automated adj bonding)) and stacked and encapsula\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/24 16:48
-	404	257/787.ccls. and metal and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/24 15:07
-	308	257/787.ccls. and metal and substrate and (pcb or (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/24 15:08